



PCIe Application Acceleration

# Fusion ioMemory™

Highest Transaction Rate/GB | Optimized for Mixed Workloads | Proven Flash Memory

Model Number	PX600-1000	PX600-1300	PX600-2600	PX600-5200
<b>Usable Capacity</b>	1,000 GB	1,300 GB	2,600 GB	5,200 GB
<b>NAND Type</b>	MLC (Multi Level Cell)	MLC (Multi Level Cell)	MLC (Multi Level Cell)	MLC (Multi Level Cell)
<b>Read Bandwidth (GB/s)</b>	2.7	2.7	2.7	2.7
<b>Write Bandwidth (GB/s)</b>	1.5	1.7*	2.2*	2.1*
<b>Ran. Read IOPS (4K)</b>	196,000	235,000	330,000	285,000
<b>Ran. Write IOPS (4K)</b>	330,000	375,000	385,000	385,000
<b>Read Access Latency</b>	92µs	92µs	92µs	92µs
<b>Write Access Latency</b>	15µs	15µs	15µs	15µs
<b>Bus Interface</b>	PCI-Express 2.0 x8			
<b>Endurance (PBW)</b>	12	16	32	64
<b>UBER</b>	1e-20			
<b>Weight</b>	5.2 ounces			7.25 ounces
<b>Form Factor</b>	Low Profile			Standard Height, Half-Length
<b>Warranty</b>	5 years or maximum endurance used			
<b>Operating Systems</b>	Microsoft Windows: Windows Server 2012 R2, Windows Server 2012, Windows 2008 R2 SP1 Linux: RHEL 5/6; SLES 11; OEL 5/6; CentOS 5/6; Debian Squeeze; Ubuntu 12/13 UNIX: Solaris 11.1/11 x64; Solaris 10 U11 x64 Hypervisors: VMware ESXi 5.0/5.1/5.5, Windows Server 2012 with Hyper-V, Windows Server 2012 R2 with Hyper-V			

\*Write BW achieved with optional high power mode. Maximum Write bandwidth performance of 1.6 GB/s achievable within 25 W power limit

## Agency

<b>US/Canada</b>	FCC Title 47, Part 15 Subpart B, Class A, CAN ICES-3 (A) NMB-3 (A) EN 55022: 2010, EN 61000-3-2: 2006 plus A1:2009 & A2:2009, EN 61000-3-3: 2008, EN 55024: 2010
<b>Europe/CE</b>	VCCI V-3/2013.04 ClassA & EN 55022 (2010) Class A, ANSI C63.4: 2009
<b>Japan/VCCI</b>	BSMI CNS 13438: 2006 Class A, EN 55022 (2006)A1 (2007) Class A
<b>Taiwan</b>	AS/NZS CISPR 22: 2009 plus A1:2010
<b>Australia/New Zealand</b>	MSIP-REM-FIO-ioMemoryPX600
<b>Korea</b>	Directive: 2006/95/EC, EN 60950-1:2006 + A11:2009 + A1:2010 + A12:2011 and IEC 60950-1:2005 + A1:2009
<b>Low Voltage Directive Testing</b>	DIRECTIVE 2011/65/EU
<b>RoHS</b>	Regulation (EC) No 1907/2006
<b>REACH</b>	Directive 2002/96/EC
<b>WEEE</b>	

## Environmental Specifications

		Min	Max
<b>Temperature<sup>1</sup></b>	Operational	0°C	55°C
	Non-operational	-40°C	70°C
<b>Power Requirements</b>			25 W
<b>Air Flow (LFM)<sup>2</sup></b>		300	
<b>Humidity (%)</b>	Non-condensing	5	95
	Operational	-1,000	10,000
<b>Altitude (ft)</b>	Non-operational	-1,000	30,000

Specifications subject to change without notice. Performance results are based on internal testing and use. Results and performance may vary according to configurations and systems, including drive capacity, system architecture and applications.

<sup>1</sup> Temperature derated 1°C per 1000 ft. elevation above sea level  
<sup>2</sup> Fusion ioMemory is designed for server platforms only and relies on 300 LFM (min) airflow, which is required for normal operation in server environments.

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